

Title (en)  
TRIMMING METHOD FOR A TEMPERATURE SENSOR

Publication  
**EP 0150784 B1 19890628 (DE)**

Application  
**EP 85100547 A 19850119**

Priority  
• CH 5485 A 19850108  
• CH 46284 A 19840201

Abstract (en)  
[origin: WO8503570A1] The process for adjusting a temperature probe with trim lines provided for adjustment purposes is characterized by the following steps: the temperature probe is brought before the measuring process to a temperature balance, the value of the temperature probe which depends on the temperature is measured in a further measuring process, a combination of interruptions of the trim lines is deduced from the temperature-dependent measured value and from the temperature value of the heat equilibrium state, said interruptions are then executed in an adjustment process. In a resistance temperature probe, the substrate is brought with the trim lines before the measuring process to a predetermined temperature, the temperature balance state is monitored, the resistance of the temperature probe is then measured in a measuring process, a combination of interruptions of a plurality of trim lines of the resistance is deduced from the measured resistance value and from the temperature value of the equilibrium state and those interruptions are finally executed in the adjustment process. The temperature probe manufactured according to the method of the present invention is provided with a conducting track structure for forming the resistance thereof, with a partial structure, with a plurality of trim lines mounted in the partial structure in parallel to the conducting track and provided for an interruption during the adjustment process; it is characterized in that the configuration of the trim lines is such that combinations of interruption of trim lines enable a computable coding of the resistance value increase of the temperature probe and in that the trim lines of said coding are interrupted.

IPC 1-7  
**G01K 7/18; G01K 7/22; H01C 17/24**

IPC 8 full level  
**G01K 7/18** (2006.01); **G01K 7/22** (2006.01); **H01C 17/23** (2006.01); **H01C 17/232** (2006.01); **H01C 17/24** (2006.01)

CPC (source: EP US)  
**G01K 7/183** (2013.01 - EP US); **G01K 7/223** (2013.01 - EP US); **H01C 17/23** (2013.01 - EP US); **H01C 17/232** (2013.01 - EP US)

Citation (examination)  
• Elektronik heute, Polyscope plus 14-15/87  
• Forschung und Technik, Neue Zürcher Zeitung Nr. 57

Cited by  
DE3630393A1; US5432375A; DE4438892A1; EP0740135A3; US5555246A

Designated contracting state (EPC)  
AT BE CH DE FR GB IT LI LU NL SE

DOCDB simple family (publication)  
**EP 0150784 A2 19850807; EP 0150784 A3 19850925; EP 0150784 B1 19890628**; AT E44317 T1 19890715; AU 3837585 A 19850827; DE 3571276 D1 19890803; US 4840494 A 19890620; WO 8503570 A1 19850815

DOCDB simple family (application)  
**EP 85100547 A 19850119**; AT 85100547 T 19850119; AU 3837585 A 19850123; CH 8500010 W 19850123; DE 3571276 T 19850119; US 10667887 A 19871013